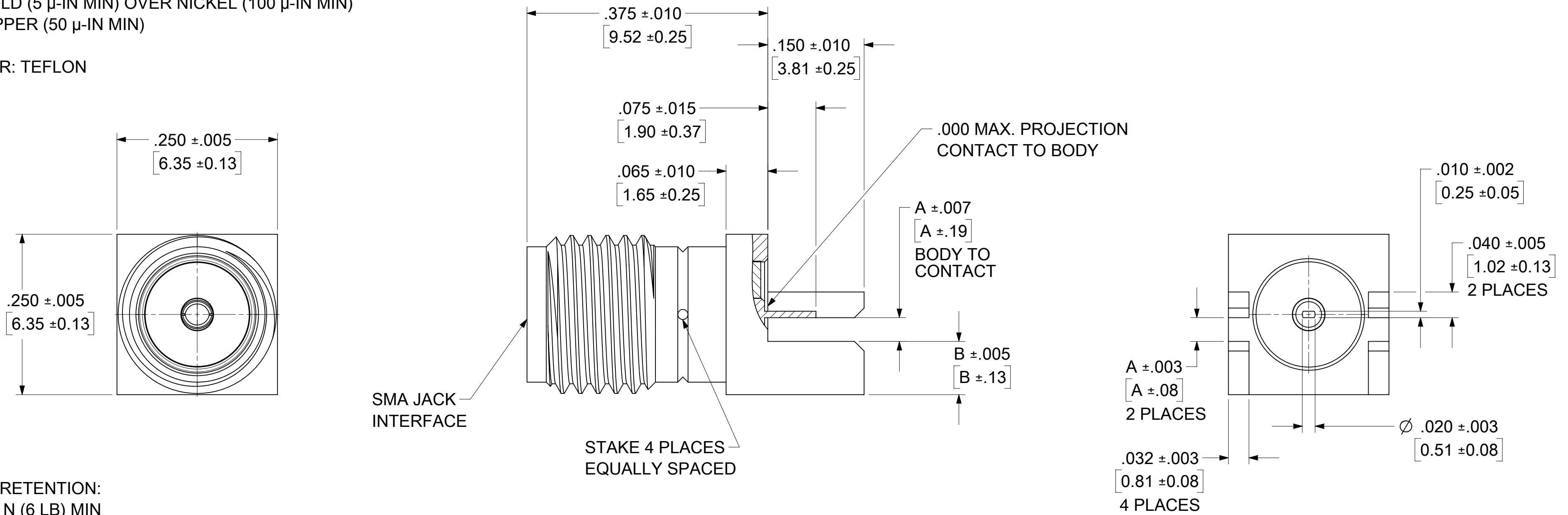
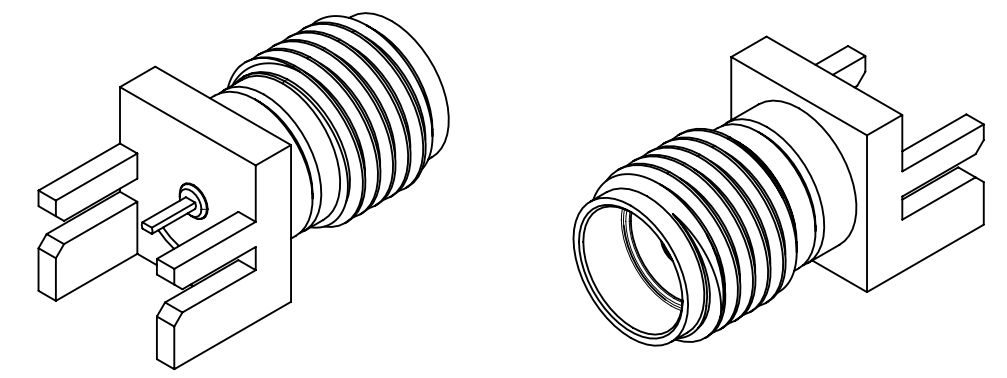


MATERIALS AND FINISHES:

BODY: BRASS
 73251-4430, -4431, -4432
 FINISH GOLD (10 μ-IN MIN) OVER NICKEL (100 μ-IN MIN)
 OVER COPPER (50 μ-IN MIN)
 73251-4433
 FINISH GOLD (1 μ-IN MIN) OVER NICKEL (100 μ-IN MIN)
 OVER COPPER (50 μ-IN MIN)

CONTACT: BERYLLIUM COPPER
 73251-4430, -4431, -4432
 FINISH GOLD (10 μ-IN MIN) OVER NICKEL (50 μ-IN MIN)
 OVER COPPER (50 μ-IN MIN)
 73251-4433
 FINISH GOLD (5 μ-IN MIN) OVER NICKEL (100 μ-IN MIN)
 OVER COPPER (50 μ-IN MIN)

INSULATOR: TEFLON



CONTACT RETENTION:
 AXIAL 26.7 N (6 LB) MIN
 TORQUE 2.82 N-CM (4 IN-OZ) MIN

UL FILE NUMBER E107635

73251-4433	.048	1.22	.072	1.83	BY TRAY, PER 89542-0040
73251-4432	.068	1.73	.052	1.32	
73251-4431	.048	1.22	.072	1.83	
73251-4430	.037	0.94	.083	2.11	
PART NO.	IN	MM	IN	MM	PACKAGING
DIM (X)	DIM A		DIM B		

MIL-STD-348A, FIG.310.2	SMA JACK INTERFACE
PS-89675-346	PRODUCT SPECIFICATION
SPECIFICATION	DESCRIPTION

FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC: ADD PKG NOTE PER EWR15242-A	
FA = 0	DIMENSION UNITS	SCALE		
EC = 0	IN/MM	NTS		
EP = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)			
	ANGULAR TOL ± 2.0°			
	4 PLACES ±		EC NO: 709659	
	3 PLACES ±		DRWN: CWEI02	2022/06/06
	2 PLACES ±		CHK'D: YCHENG	2022/06/15
	1 PLACE ±		APPR: YCHENG	2022/06/15
	0 PLACES ±		INITIAL REVISION:	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRWN: JLEE02	2011/03/07
	THIRD ANGLE PROJECTION		APPR: JWIENER	2011/04/11
	DRAWING		SERIES	
	C-SIZE		73251	
	MATERIAL NUMBER		CUSTOMER	SHEET NUMBER
	SEE TABLE		GENERAL MARKET	1 OF 1

molex

SMA JACK, PCB END LAUNCH
 TAB CONTACT, EWR-4636 SMA-J/PCB

PRODUCT CUSTOMER DRAWING

SD-73251-443

PSD 001 A2